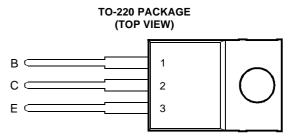
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- Designed for Complementary Use with BDW93, BDW93A, BDW93B and BDW93C
- 80 W at 25°C Case Temperature
- 12 A Continuous Collector Current
- Minimum h_{FE} of 750 at 3 V, 5 A



Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING			VALUE	UNIT	
	BDW94		-45		
Collector-base voltage $(I_E = 0)$	BDW94A	V	-60	V	
	BDW94B	V _{CBO}	-80	v	
	BDW94C		-100		
	BDW94		-45		
Callector emitter veltere (I)	BDW94A	V	-60	V	
Collector-emitter voltage ($I_B = 0$)	BDW94B	V _{CEO}	-80		
	BDW94C		-100		
Emitter-base voltage			-5	V	
Continuous collector current			-12	A	
Continuous base current			-0.3	А	
Continuous device dissipation at (or below) 25°C case temperature (see Note 1)			80	W	
Continuous device dissipation at (or below) 25°C free air temperature (see Note 2)			2	W	
Operating junction temperature range			-65 to +150	°C	
Storage temperature range			-65 to +150	°C	
Operating free-air temperature range			-65 to +150	°C	

NOTES: 1. Derate linearly to 150°C case temperature at the rate of 0.64 W/°C.

2. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.





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electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	ТҮР	MAX	UNIT	
V _{(BR)CEO}	Collector-emitter breakdown voltage	I _C = -100 mA	I _B = 0	(see Note 3)	BDW94 BDW94A	-45 -60			V
					BDW94B BDW94C	-80 -100			v
I _{CEO}	Collector-emitter cut-off current	V _{CB} = -40 V	$I_B = 0$		BDW94			-1	
		V _{CB} = -60 V	$I_B = 0$		BDW94A			-1	mA
		V _{CB} = -80 V	$I_B = 0$		BDW94B			-1	
		V _{CB} = -80 V	$I_B = 0$		BDW94C			-1	
I _{CBO}		V _{CB} = -45 V	$I_E = 0$		BDW94			-0.1	
		V _{CB} = -60 V	$I_E = 0$		BDW94A			-0.1	
		$V_{CB} = -80 V$	$I_E = 0$		BDW94B			-0.1	
	Collector cut-off current	$V_{CB} = -100 V$	$I_E = 0$		BDW94C			-0.1	mA
		$V_{CB} = -45 V$	$I_E = 0$	$T_{\rm C} = 150^{\circ}{\rm C}$	BDW94			-5	IIIA
		V _{CB} = -60 V	$I_E = 0$	$T_{\rm C} = 150^{\circ}{\rm C}$	BDW94A			-5	
		$V_{CB} = -80 V$	$I_E = 0$	$T_{\rm C} = 150^{\circ}{\rm C}$	BDW94B			-5	
		$V_{CB} = -100 V$	$I_E = 0$	$T_{\rm C} = 150^{\circ}{\rm C}$	BDW94C			-5	
I _{EBO}	Emitter cut-off current	V _{EB} = -5 V	$I_{\rm C} = 0$					-2	mA
h _{FE}	Forward current transfer ratio	V _{CE} = -3 V	I _C = -3 A			1000			
		$V_{CE} = -3 V$	$I_{\rm C} = -10 {\rm A}$	(see Notes 3 and	d 4)	100			
		$V_{CE} = -3 V$	I _C = -5 A			750		20000	
V _{CE(sat)}	Collector-emitter	I _B = -20 mA	I _C = -5 A	(see Notes 3 and 4)				-2	V
	saturation voltage	$I_B = -100 \text{ mA}$	$I_{\rm C} = -10 {\rm A}$					-3	v
V _{BE(sat)}	Base-emitter	I _B = -20 mA	I _C = -5 A	(see Notes 3 and 4)				-2.5	V
	saturation voltage	$I_{B} = -100 \text{ mA}$	$I_{\rm C} = -10 {\rm A}$					-4	•
V_{EC}	Parallel diode	I _E = -5 A	$I_B = 0$					-2	V
	forward voltage	I _E = -10 A	$I_B = 0$					-4	•

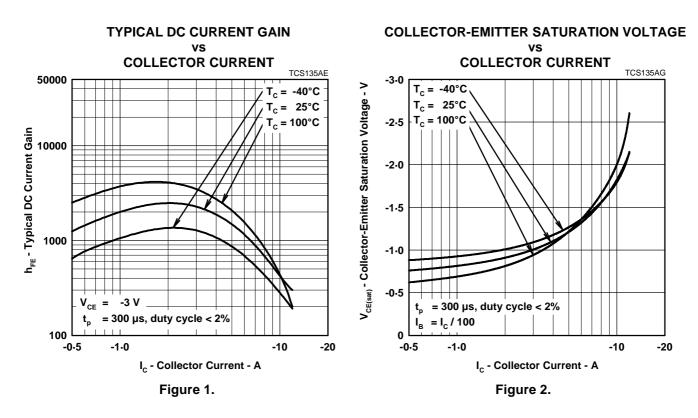
NOTES: 3. These parameters must be measured using pulse techniques, t_p = 300 $\mu s,$ duty cycle \leq 2%.

4. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

thermal characteristics

PARAMETER		MIN	TYP	MAX	UNIT
R _{θJC}	Junction to case thermal resistance			1.56	°C/W
R _{θJA}	Junction to free air thermal resistance			62.5	°C/W

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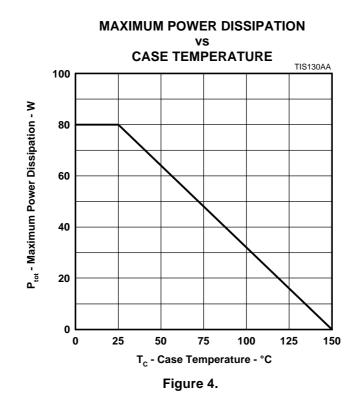
TYPICAL CHARACTERISTICS

BASE-EMITTER SATURATION VOLTAGE vs **COLLECTOR CURRENT** TCS135AI -3-0 $T_c = -40^{\circ}C$ V_{BE(sat)} - Base-Emitter Saturation Voltage - V 25°C T_c = = 100°C Tc -2.5 -2-0 -1-5 -1-0 $= I_c / 100$ = 300 µs, duty cycle < 2% t, -0-5 -1-0 -0-5 -10 -20 I_c - Collector Current - A





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THERMAL INFORMATION

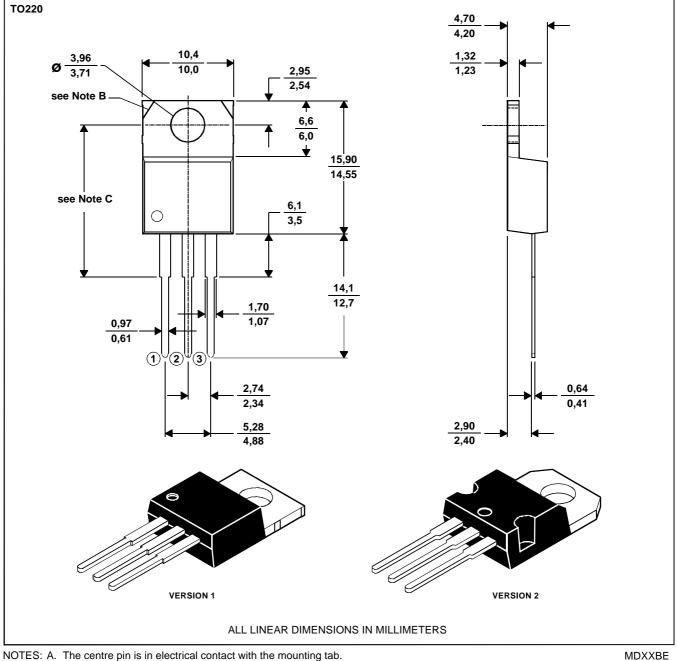
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MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



B. Mounting tab corner profile according to package version.

C. Typical fixing hole centre stand off height according to package version.

Version 1, 18.0 mm. Version 2, 17.6 mm.

PRODUCT INFORMATION

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